Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D
			**** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2023-02-02
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	**Representative Title**	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	**Legal Declaration ***	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Signature Not
Verified

Digitally signed by
MDF Champion
Date: 2023.02.02
08:46:34 -08:00

Product

Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32U585RIT6Q STM32U585RIT6QTR	735W*482XXXX	A	998Z	2023-02-02
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	363.27	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information

J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	
3	260	3	
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy	

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10	64	L bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**735W*482XXXX**				6000000.0	1000007.1
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	14.654	mg	supplier	die	Silicon (Si)	7440-21-3		14.083	mg	961035	38767
				supplier	metallization	Aluminium (Al)	7429-90-5		0.063	mg	4299	173
				supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	12829	518
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	68	3
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.032	mg	2184	88
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	546	22
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	68	3
				supplier	Passivation	Silicon Nitride	12033-89-5		0.045	mg	3071	124
				supplier	Passivation	Silicon Oxide	7631-86-9		0.233	mg	15900	641
Glue epoxy (3230)	M-011 Other inorganic materials	1.993	mg	Supplier	Metals	Silver	7440-22-4		1.625	mg	815000	4472
				Supplier	Plastics/polymers	2,2'-[Methylenebis(phenyleneoxymethylene)]b	39817-09-9		0.060	mg	30000	165
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.060	mg	30000	165
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.060	mg	30000	165
				Supplier	Organic Compounds	Dodecyloxirane	3234-28-4		0.060	mg	30000	165
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.060	mg	30000	165
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.060	mg	30000	165
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.010	mg	5000	27
Encapsulation (EME-G631SHQ)	M-011 Other inorganic materials	240.805	mg	Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		5.057	mg	21000	13921
				Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		5.057	mg	21000	13921
				Supplier	Plastics/polymers	Phenol Resin	Trade Secret		13.485	mg	56000	37122
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		187.936	mg	780450	517351
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		27.770	mg	115320	76444
				Supplier	Non-metals	Carbon Black	1333-86-4		1.500	mg	6230	4130
Wire (Au)	Bonding Wire	1.079	mg	Supplier	Metals	Gold	7440-57-5		1.079	mg	1000000	2971
Plating Anode (Pure Tin)	M-011 Other inorganic materials	1.438	mg	Supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	3958
Leadframe (C194+Ag)	Copper & its alloys	103.300	mg	Supplier	Metals	Copper	7440-50-8		100.428	mg	972200	276459
				Supplier	Metals	Iron	7439-89-6		2.366	mg	22900	6512
				Supplier	Metals	Zinc	7440-66-6		0.155	mg	1500	427
				Supplier	Non-Metals	Phophorus	7723-14-0		0.031	mg	300	85
				Supplier	Metals	Siliver	7440-22-4		0.320	mg	3100	882